

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1-3. (Canceled)

4. (Currently Amended) The method of claim 1, A method of communicating semiconductor manufacturing information, the method comprising:
providing, by a first service provider, a lot of semiconductor components to a second service provider for processing;
receiving, by the first service provider, first information associated with the processing, from the second service provider;
generating, by the first service provider, second information responsive to the first information; and
outputting, by the first service provider, the second information to a customer affiliated with the second service provider;
wherein the first service provider includes a first manufacturing execution system (“MES”), the second provider includes a second MES, the first MES and the second MES are dissimilar.

5. (Canceled)

6. (Previously presented) A method of communicating semiconductor manufacturing information, the method comprising:
providing, by a first service provider, a lot of semiconductor components to a second service provider for processing;
receiving, by the first service provider, first information associated with the processing, from the second service provider
generating, by the first service provider, second information responsive to the first information; and

outputting, by the first service provider, the second information to a customer affiliated with the second service provider;

wherein the first information includes work-in-process (“WIP”) information, wherein the second information includes a determination of whether a time duration associated with the processing of a component of the lot exceeds a predetermined duration of time.

7-18. (Canceled)

19. (Currently Amended) The system of claim 16, A system for communicating semiconductor manufacturing information, comprising:

an information handling system (“IHS”)) associated with a first service provider for:
from a second service provider, receiving first information associated with
processing of a lot of semiconductor components, the lot having been provided by the
first service provider to the second service provider for the processing;
generating second information responsive to the first information; and
to a customer affiliated with the second service provider, outputting the second
information;

wherein the first service provider includes a first manufacturing execution system (“MES”), the second service provider includes a second MES, and the first MES and the second MES are dissimilar.

20. (Canceled)

21. (Currently Amended) The system of claim 20, A system for communicating semiconductor manufacturing information, comprising:

an information handling system (“IHS”)) associated with a first service provider for:
from a second service provider, receiving first information associated with
processing of a lot of semiconductor components, the lot having been provided by the
first service provider to the second service provider for the processing;
generating second information responsive to the first information; and

to a customer affiliated with the second service provider, outputting the second information;

wherein the first information includes work-in-process (“WIP”) information, wherein the second information includes a determination of whether a time duration associated with the processing of a component of the lot exceeds a predetermined period of time.

22-30. (Canceled)